

Developing Monomers

Company About Us Products SiteMap



Developing Monomers

CONTENTS

|| [Home](#)
Company Home

Page

|| [Products](#)

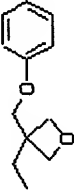



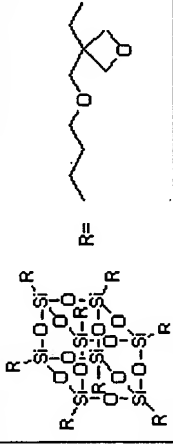
Detailed
information on our
Specialty
Chemicals..

|| [About Us](#)

Introduction to our
company and
contacts.

|| [What's New](#)

New items or
products at
Toagosei America.

Chemical Name	3-Ethyl-3-phenoxymethyl-oxetane	Bis[1-ethyl(3-oxetanyl)methyl] ether	3-Ethyl-3-[(2-ethylhexyloxy)methyl]oxetane	3-ethyl-1-[(triethoxysilylpropoxymethyl)oxetane]	Oxetanyl-Silsesquioxane
Abbreviated Name	POX	DOX	EHOX	TESOX	OX-SQ
Product Name	OXT-211	OXT-221	OXT-212	OXT-610	-
Chemical Formula					
note	-	-	-	-	model structure
Content	98% up	98% up	95% up	95% up	95% up
Molecular weight	192.3	214.3	228.4	320.5	1,000-2,000
Appearance	clear liquid	clear liquid	clear liquid	clear liquid	clear pale yellow liquid
Boiling point	130 deg. /5mmHg	119 deg. /5mmHg	133 deg. /10mmHg	128 deg. /1mmHg	-
Freezing point	-	-	-	-	-

Specific gravity (25 deg.)	1.046	0.999	0.892	-	-
Viscosity (25 deg.)	13.8 mPa/s	12.8 mPa/s	5.0 mPa/s	8 mPa/s	-
Flash point	145 (Open Cup)	144 (Open Cup)	130 (Open Cup)	156 (Open Cup)	-
Skin irritation (PII)	1.9	1.0	-	-	-
Ames test	Negative	Negative	Negative	Negative	-
,s,†	-2 (DSC)	51 (VES)	-60 (DSC)	-	-
Specific Gravity	1.098	1.056	0.922	-	-
Shrinking with Curing	4.7%	5.5%	3.8%	-	-
CAS No.	3897-65-2	18934-00-4	-	3897-65-2	-
TOSCA	not included	not included	not included	not included	not included
EINECS No.	not included	not included	not included	not included	not included
Benefits	Flexibility, high cure response	high cross-link, high cure response	high diluency, high cure response	Good adhesion	Hard coat
Main Application	Adhesives, Coatings, Inks	Adhesives, Coatings, Inks	Adhesives, Coatings, Inks	Adhesives, Coatings, Inks	Coatings
Technical Report	none	none	none	none	none



[Company] [About Us] [Products] [SiteMap]

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